



EZ-USB[®] CX3: MIPI CSI-2 to SuperSpeed USB Bridge Controller

Features

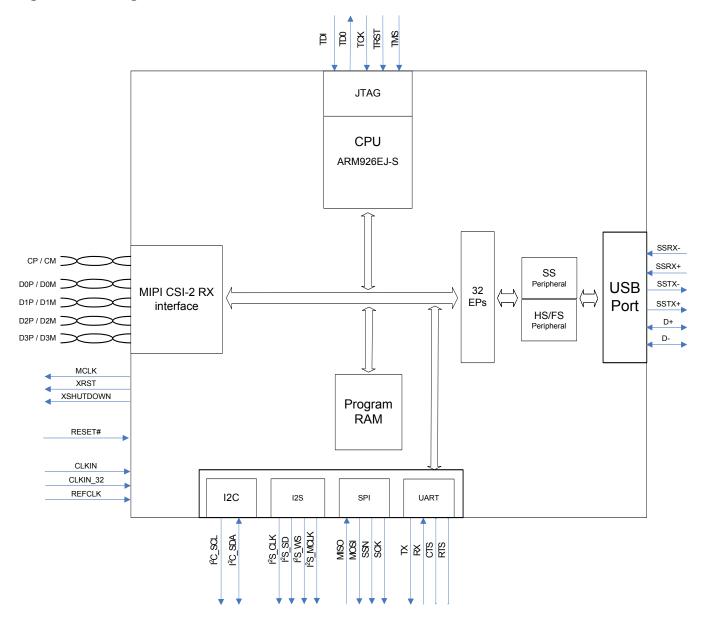
- Universal Serial Bus (USB) integration
 - □ USB 3.0 and USB 2.0 peripherals, compliant with USB 3.0 specification 1.0
 - □ 5-Gbps USB 3.0 PHY compliant with PIPE 3.0
 - □ Thirty-two physical endpoints
- MIPI CSI-2 RX interface
 - ☐ MIPI CSI-2 compliant (Version 1.01, Revision 0.04 2nd April 2009)
 - □ Supports up to four data lanes (CYUSB3065 supports up to four lanes; CYUSB3064 supports up to two lanes)
 - □ Each lane supports up to 1 Gbps (CYUSB3065 supports up to four lanes; CYUSB3064 supports up to two lanes)
 - CCI interface for image sensor configuration
- Supports the following video data formats:
 - □ User-defined 8-bit
 - □ RAW8/10/12/14
 - □ YUV422 (CCIR/ITU 8/10bit), YUV444
 - □ RGB888/666/565
- Fully accessible 32-bit CPU
 - □ ARM926EJ-S core with 200-MHz operation
 - □ 512-KB or 256-KB embedded SRAM
- Additional connectivity to the following peripherals:
 - □ I²C master controller at 1 MHz
 - □ I²S master (transmitter only) at sampling frequencies of 32 kHz, 44.1 kHz, and 48 kHz
 - □ UART support of up to 4 Mbps
 - □ SPI master at 33 MHz
- Twelve GPIOs
- Ultra-low-power in core power-down mode
- Independent power domains for core and I/O
 - □ Core operation at 1.2 V
 - □ I²S, UART, and SPI operation at 1.8 to 3.3 V
 - □ I²C, I/O operation at 1.8 to 3.3 V
- 10 × 10 mm, 0.8-mm pitch Pb-free ball grid array (BGA) package
- EZ-USB[®] software development kit (SDK) for easy code development

Applications

- Digital video cameras
- Digital still cameras
- Webcams
- Scanners
- Video conference systems
- Gesture-based control
- Surveillance cameras
- Medical imaging devices
- Video IP phones
- USB microscopes
- Industrial cameras



Logic Block Diagram





More Information

Cypress provides a wealth of data at www.cypress.com to help you to select the right device for your design, and to help you to quickly and effectively integrate the device into your design. For a comprehensive list of resources refer to the cypress web page for CX3 at www.cypress.com/CX3.

- Overview: USB Portfolio, USB Roadmap
- USB 3.0 Product Selectors: FX3, FX3S, CX3, GX3, HX3, West Bridge Benicia
- Application notes: Cypress offers a large number of USB application notes covering a broad range of topics, from basic to advanced level. Recommended application notes for getting started with CX3 are:
 - □ AN75705 Getting Started with EZ-USB FX3
 - □ AN90369 How to Interface a MIPI CSI-2 Image Sensor With EZ-USB® CX3
 - □ AN75779 How to Implement an Image Sensor Interface with EZ-USB® FX3™ in a USB Video Class (UVC) Framework
 - □ AN76405 EZ-USB FX3 Boot Options
 - □ AN70707 EZ-USB FX3/FX3S Hardware Design Guidelines and Schematic Checklist
 - □ AN86947 Optimizing USB 3.0 Throughput with EZ-USB FX3
- Code Examples:
 - □ USB SuperSpeed
- Technical Reference Manual (TRM):
 - □ EZ-USB® CX3 Technical Reference Manual

■ Knowledge Base Articles:

- CX3 Firmware: Frequently Asked Questions KBA91297
- □ CX3 Hardware: Frequently Asked Questions KBA91295
- CX3 Application Software / USB Driver: Frequently Asked Questions - KBA91298
- □ Knowledge Base Cypress Semiconductor Cage Code -KBA89258

■ Development Kits:

- □ Ascella Cypress® CX3™ THine® ISP 13MP reference design kit (RDK)
- □ Denebola USB 3.0 UVC Reference Design Kit (RDK)

Models

- □ CX3 Device OrCad Schematic Symbol
- □ CYUSB306x IBIS

EZ-USB Software Development Kit

Cypress delivers the complete firmware stack for CX3, in order to easily integrate SuperSpeed USB into any embedded MIPI image sensor application. The Software Development Kit (FX3 SDK) comes with tools, drivers and application examples, which help accelerate application development. The FX3 SDK Setup includes CX3 APIs and example firmware for OmniVision OV5640 and Aptina AS0260 image sensor interface. The eclipse plugin for the FX3 SDK accelerates CX3 firmware development for any other image sensor.



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Functional Overview

Cypress's EZ-USB CX3 is the next-generation bridge controller that can connect devices with the Mobile Industry Processor Interface – Camera Serial Interface 2 (MIPI CSI-2) interface to any USB 3.0 Host.

CX3 has a 4-lane CSI-2 receiver with up to 1 Gbps on each lane. It supports video data formats such as RAW8/10/12/14, YUV422 (CCIR/ITU 8/10-bit), RGB888/666/565, and user-defined 8-bit.

CX3 has integrated the USB 3.0 and USB 2.0 physical layers (PHYs) along with a 32-bit ARM926EJ-S microprocessor for powerful data processing and for building custom applications.

CX3 contains 512 KB of on-chip SRAM (see Ordering Information on page 27) for code and data. EZ-USB CX3 also provides interfaces to connect to serial peripherals such as UART, SPI, I²C, and I²S.

CX3 comes with application development tools. The software development kit comes with application examples for accelerating time-to-market.

CX3 complies with the USB 3.0 v1.0 specification and is also backward compatible with USB 2.0. It also complies with the MIPI CSI-2 v1.01, revision 0.04 specification dated 2nd April 2009.

Application Examples

In a typical application (see Figure 1), CX3 acts as the main processor and connects to an image sensor, an audio device, or camera control devices amongst others.

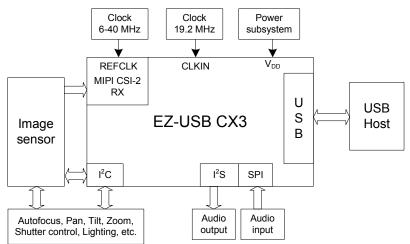


Figure 1. EZ-USB CX3 Example Application

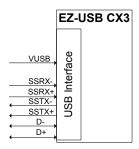


USB Interface

CX3 complies with the following specifications and supports the following features:

- Supports USB peripheral functionality compliant with USB 3.0 Specification, Revision 1.0, and is also backward compatible with the USB 2.0 Specification.
- As a peripheral, CX3 is capable of SuperSpeed, High-Speed, and Full-Speed.
- Supports up to 16 IN and 16 OUT endpoints
- Supports the USB 3.0 Streams feature
- As a USB peripheral, CX3 supports USB-attached storage (UAS), USB Video Class (UVC), and Media Transfer Protocol (MTP) USB peripheral classes. As a USB peripheral, all other device classes are supported only in pass-through mode when handled entirely by a host processor external to the device.

Figure 2. USB Interface Signals



ReNumeration

Because of CX3's soft configuration, one chip can take on the identities of multiple distinct USB devices.

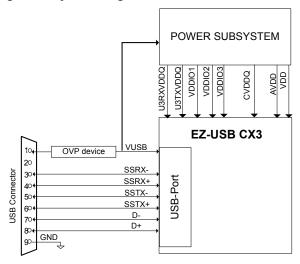
When first plugged into USB, CX3 enumerates automatically with the Cypress Vendor ID (0x04B4) and downloads the firmware and USB descriptors over the USB interface. The downloaded firmware executes an electrical disconnect and connect. CX3 enumerates again, this time as a device defined by the downloaded information. This patented two-step process, called ReNumeration, happens instantly when the device is plugged in.

VBUS Overvoltage Protection

The maximum input voltage on CX3's VUSB pin is 6 V. A charger can supply up to 9 V on VUSB. In this case, an external overvoltage protection (OVP) device is required to protect CX3 from damage on VUSB. Figure 3 shows the system application diagram with an OVP device connected on VUSB. Refer to DC Specifications on page 17 for the operating range of VUSB.

Note: The VBUS pin of the USB connector should be connected to the VUSB pin of CX3.

Figure 3. System Diagram with OVP Device For VUSB





MIPI CSI-2 RX Interface

The Mobile Industry Processor Interface (MIPI) association defined the Camera Serial Interface 2 (CSI-2) standard to enable image data to be sent on high-bandwidth serial lines.

CX3 implements a MIPI CSI-2 Receiver with the following features:

- It can receive clock and data in 1, 2, 3, or 4 lanes. (CYUSB3065 part supports up to four lanes; CYUSB3064 part supports up to two lanes)
- 2. Up to 1 Gbps of data on each CSI lane is supported (total maximum bandwidth should not exceed 2.4 Gbps).
- Video formats such as RAW8/10/12/14, YUV422 (CCIR/ITU 8/10-bit), RGB888/666/565, and User-Defined 8-bit are supported
- A CCI interface (compatible with 100-kHz or 400-kHz I²C interface with 7-bit addressing) is provided to configure the sensor.
- GPIOs are available for synchronization of external flash or lighting system with image sensors to illuminate the scene that improves the image quality by improving Signal to noise ratio.
- GPIOs can also be used to synchronize the image sensor with external events, so that image can be captured based on external event.
- Serial interfaces (such as I²C, I²S, SPI, UART) are available to implement camera functions such as Auto focus and Pan, Tilt, Zoom (PTZ)

Additional Outputs

In addition to the standard MIPI CSI-2 signals, the following three additional outputs are provided:

- 1. XRST: this can be used to reset the image sensor
- XSHUTDOWN: this pin can be used to put the sensor to a standby/shutdown mode
- MCLK: this pin can provide the clock output. It can be used only for testing the image sensor. For production, use an external clock generator as clock input for image sensors.

CPU

CX3 has an on-chip 32-bit, 200-MHz ARM926EJ-S core CPU. The core has direct access to 16 kB of Instruction Tightly Coupled Memory (TCM) and 8 kB of data TCM. The ARM926EJ-S core provides a JTAG interface for firmware debugging.

CX3 offers the following advantages:

- Integrates 512 KB of embedded SRAM for code and data and 8 kB of instruction cache and data cache.
- Implements efficient and flexible DMA connectivity between the various peripherals (such as, USB, CSI-2 Rx, I²S, SPI, and UART), requiring firmware only to configure data accesses between peripherals, which are then managed by the DMA fabric.
- Allows easy application development on industry-standard development tools for ARM926EJ-S.

Examples of the CX3 firmware are available with the Cypress EZ-USB CX3 Development Kit. Software APIs that can be ported to an external processor are available with the Cypress EZ-USB CX3 Software Development Kit.

JTAG Interface

CX3's JTAG interface has a standard five-pin interface to connect to a JTAG debugger in order to debug firmware through the CPU-core's on-chip-debug circuitry.

Industry-standard debugging tools for the ARM926EJ-S core can be used for the CX3 application development.

Other Interfaces

CX3 supports the following serial peripherals:

- **■** UART
- I²C
- I²S
- SPI

The CYUSB306X Pin List on page 15 shows the details of how these interfaces are mapped.

UART Interface

The UART interface of CX3 supports full-duplex communication. It includes the signals noted in Table 1.

Table 1. UART Interface Signals

Signal	Description	
TX	Output signal	
RX	Input signal	
CTS	Flow control	
RTS	Flow control	

The UART is capable of generating a range of baud rates, from 300 bps to 4608 Kbps, selectable by the firmware. If flow control is enabled, then CX3's UART only transmits data when the CTS input is asserted. In addition to this, CX3's UART asserts the RTS output signal, when it is ready to receive data.

I²C Interface

CX3's I²C interface is compatible with the I²C Bus Specification Revision 3. This I²C interface is capable of operating only as I²C master; therefore, it may be used to communicate with other I²C slave devices. For example, CX3 may boot from an EEPROM connected to the I²C interface, as a selectable boot option.

CX3's I²C Master Controller also supports multi-master mode functionality.

The power supply for the I^2C interface is V_{DDIO1} , which is a separate power domain from the other serial peripherals. This gives the I^2C interface the flexibility to operate at a different voltage than the other serial interfaces.



The $\rm I^2C$ controller supports bus frequencies of 400 kHz, and 1 MHz. When $\rm V_{DDIO1}$ is 1.8 V, 2.5 V, or 3.3 V, the operating frequencies supported are 400 kHz and 1 MHz. The $\rm I^2C$ controller supports the clock-stretching feature to enable slower devices to exercise flow control.

The I^2C interface's SCL and SDA signals require external pull-up resistors. The pull-up resistors must be connected to V_{DDIO1} .

Note: I²C addresses with the pattern 0x0000111x are used internally and no slave devices with those addresses should be connected to the bus.

I²S Interface

CX3 has an I²S port to support external audio codec devices. CX3 functions as I²S Master as transmitter only. The I²S interface consists of four signals: clock line (I2S_CLK), serial data line (I2S_SD), word select line (I2S_WS), and master system clock (I2S_MCLK). CX3 can generate the system clock as an output on I2S_MCLK or accept an external system clock input on I2S_MCLK.

The sampling frequencies supported by the I²S interface are 32 kHz, 44.1 kHz, and 48 kHz.

SPI Interface

CX3 supports an SPI Master interface on the Serial Peripherals port. The maximum operation frequency is 33 MHz.

The SPI controller supports four modes of SPI communication (see SPI Timing Specification on page 24 for details on the modes) with the Start-Stop clock. This controller is a single-master controller with a single automated SSN control. It supports transaction sizes ranging from 4 bits to 32 bits.

Boot Options

CX3 can load boot images from various sources, selected by the configuration of the PMODE pins. Following are the CX3 boot options:

- Boot from USB
- Boot from I²C
- Boot from SPI (SPI devices supported are M25P16 (16 Mbit), M25P80 (8 Mbit), and M25P40 (4 Mbit)) or their equivalents

Table 2. CX3 Booting Options

PMODE[2:0] ^[1]	Boot From
F11	USB boot
F1F	I ² C, On failure, USB boot is enabled
1FF	I ² C only
0F1	SPI, On failure, USB boot is enabled

Reset

Hard Reset

A hard reset is initiated by asserting the RESET# pin on CX3. The specific reset sequence and timing requirements are detailed in Figure 11 on page 26 and Table 14 on page 26. All I/Os are tristated during a hard reset.

An additional reset pin called MIPI_RESET is provided that resets the MIPI CSI-2 core. It should be pulled down with a resistor for normal operation.

Soft Reset

There are two types of Soft Reset:

- CPU Reset The CPU Program Counter is reset. Firmware does not need to be reloaded following a CPU Reset.
- Whole Device Reset This reset is identical to Hard Reset. The firmware must be reloaded following a Whole Device Reset.

F indicates Floating.



Clocking

CX3 requires two clocks for normal operation:

- 1. A 19.2-MHz clock to be connected at the CLKIN pin
- 2. A 6-MHz to 40-MHz clock to be connected at the REFCLK pin Clock inputs to CX3 must meet the phase noise and jitter requirements specified in Table 3 on page 9.

Table 3. CX3 Input Clock Specifications

The input clock frequency is independent of the clock and data rate of the CX3 core or any of the device interfaces (including the CSI-2 Rx Port). The internal PLL applies the appropriate clock-multiply option depending on the input frequency.

Note: REFCLK and CLKIN must have either separate clock inputs or if the same source is used, the clock must be passed through a buffer with two outputs and then connected to the clock pins.

Parameter	Description	Specifi	Units		
Faranietei	Description	Min	Max	Oillis	
	100-Hz offset	-	– 75	dB	
	1-kHz offset	-	-104	dB	
Phase noise	10-kHz offset	-	-120	dB	
	100-kHz offset	-	-128	dB	
	1-MHz offset	_	-130	dB	
Maximum frequency deviation	_	-	150	ppm	
Duty cycle	_	30	70	%	
Overshoot	_	_	3	%	
Undershoot	-	_	-3	%	
Rise time/fall time	_	_	3	ns	

32-kHz Watchdog Timer Clock Input

CX3 includes a watchdog timer. The watchdog timer can be used to interrupt the ARM926EJ-S core, automatically wake up the CX3 in Standby mode, and reset the ARM926EJ-S core. The watchdog timer runs a 32-kHz clock, which may be optionally supplied from an external source on a dedicated CX3 pin.

The firmware can disable the watchdog timer.

Table 4 provides the requirements for the optional 32-kHz clock input

Table 4. 32-kHz Clock Input Requirements

Parameter	Min	Max	Units
Duty cycle	40	60	%
Frequency deviation	_	±200	ppm
Rise time/fall time	_	200	ns



Power

CX3 has the following power supply domains:

- IO_VDDQ: This is a group of independent supply domains for digital I/Os.
 - $\hfill\Box \mbox{ V_{DDIO1}: GPIO, I^2C, JTAG, XRST, XSHUTDOWN and REFCLK$
 - □ V_{DDIO2}: UART and I²S (except MCLK)
 - □ V_{DDIO3}: I²S_MCLK and SPI
 - □ C_{VDDQ}: CLKIN
 - □ V_{DD MIPI}: MIPI CSI-2 clock and data lanes
- V_{DD}: This is the supply voltage for the logic core. The nominal supply-voltage level is 1.2 V. This supplies the core logic circuits. The same supply must also be used for the following:
 - □ A_{VDD}: This is the 1.2 V supply for the PLL, crystal oscillator, and other core analog circuits.
 - □ U3TXVDDQ/U3RXVDDQ: These are the 1.2 V supply voltages for the USB 3.0 interface.
- VUSB: This is the 4 V to 6 V power supply for the USB I/O and analog circuits. This supply powers the USB transceiver through CX3's internal voltage regulator. VUSB is internally regulated to 3.3 V.

Note: The different power supplies have to be powered on or off in a specific sequence as illustrated in Figure 4.

Power Modes

CX3 supports the following power modes:

- Normal mode: This is the full-functional operating mode. The internal CPU clock and the internal PLLs are enabled in this mode.
 - □ Normal operating power consumption does not exceed the sum of $\rm I_{CC}$ Core max and $\rm I_{CC}$ USB max (see DC Specifications on page 17 for current consumption specifications).
 - $\hfill\Box$ The I/O power supplies V_{DDIO2} and V_{DDIO3} can be turned off when the corresponding interface is not in use. V_{DDIO1} should never be turned off for normal operation.
- Low-power modes (see Table 5 on page 11):
 - □ Suspend mode with USB 3.0 PHY enabled
 - □ Standby mode
- □ Core power-down mode

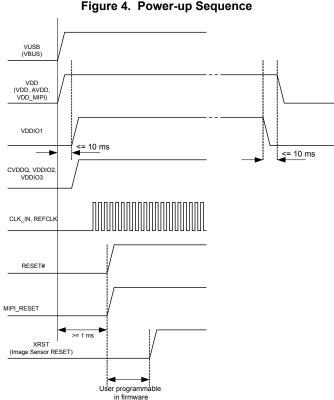




Table 5. Entry and Exit Methods for Low-Power Modes

Low-Power Mode	Characteristics	Methods of Entry	Methods of Exit
	■ Power consumption in this mode does not exceed I _{SB1}		
	■ USB 3.0 PHY is enabled and is in U3 mode (one of the suspend modes defined by the USB 3.0 specification). This one block alone is operational with its internal clock, while all other clocks are shut down		■ D+ transitioning to low or high
	■ All I/Os maintain their previous state		■ D- transitioning to low
Suspend Mode with USB 3.0 PHY	■ Power supply for the wakeup source and core power must be retained. All other power domains can be turned on or off individually	■ Firmware executing on ARM926EJ-S core can put CX3 into the suspend mode. For example, on	or high ■ Resume condition on SSRX±
Enabled	■ The states of the configuration registers,	USB suspend condition, the firmware may decide to put CX3 into suspend	■ Detection of VBUS
	buffer memory, and all internal RAM are maintained	mode	■ Level detect on UART_CTS (programmable
	■ All transactions must be completed before CX3 enters suspend mode (state of		polarity)
	outstanding transactions are not preserved)		■ Assertion of RESET#
	■ The firmware resumes operation from where it was suspended (except when woken up by RESET# assertion) because the program counter does not reset		
	■ The power consumption in this mode does not exceed ISB3		
	■ All configuration register settings and program/data RAM contents are preserved. However, data in the buffers or other parts of the data path, if any, is not guaranteed. Therefore, the external processor should take care that the data needed is read before putting CX3 into the standby mode		■ Detection of VBUS
	■ The program counter is reset after waking	■ The firmware executing on	■ Level detect on
Standby Mode	up from the standby mode ■ GPIO pins maintain their configuration	ARM926EJ-S core or external processor configures the appropriate	UART_CTS (programmable
	■ Internal PLL is turned off	register	polarity)
	■ USB transceiver is turned off		■ Assertion of RESET#
	■ ARM926EJ-S core is powered down. Upon wakeup, the core re-starts and runs the program stored in the program/data RAM		
	■ Power supply for the wakeup source and core power must be retained. All other power domains can be turned on or off individually		



Table 5. Entry and Exit Methods for Low-Power Modes (continued)

Low-Power Mode	Characteristics	Methods of Entry	Methods of Exit
	■ The power consumption in this mode does not exceed ISB ₄		
	■ Core power is turned off		
Core Power-down Mode	■ All buffer memory, configuration registers, and the program RAM do not maintain state. After exiting this mode, reload the firmware	■ Turn off V _{DD}	■ Reapply V_{DD}■ Assertion of RESET#
	■ In this mode, all other power domains can be turned on or off individually		



Configuration Options

Configuration options are available for specific usage models. Contact Cypress Marketing (usb3@cypress.com) for details.

Digital I/Os

CX3 has internal firmware-controlled pull-up or pull-down resistors on all digital I/O pins. An internal 50-k Ω resistor pulls the pins high, while an internal 10-k Ω resistor pulls the pins low to prevent them from floating. The I/O pins may have the following states:

- Tristated (High-Z)
- Weak pull-up (via internal 50 kΩ)
- Pull-down (via internal 10 kΩ)
- Hold (I/O hold its value) when in low-power modes
- The JTAG TDI, TMC, and TRST# signals have fixed 50-k Ω internal pull-ups, and the TCK signal has a fixed 10-k Ω pull-down resistor.

All unused I/Os should be pulled high by using the internal pull-up resistors. All unused outputs should be left floating. All I/Os can be driven at full-strength, three-quarter strength, half-strength, or quarter-strength. These drive strengths are configured separately for each interface.

GPIOs

CX3 provides 12 pins for general purpose I/O (for example, can be used for lighting, sync-in, sync-out and so on). See Pin Configuration on page 14 for pinout details.

All GPIO pins support an external load of up to 16 pF for every pin.

EMI

CX3 can meet EMI requirements outlined by FCC 15B (USA) and EN55022 (Europe) for consumer electronics at system level. CX3 can tolerate reasonable EMI, conducted by the aggressor, outlined by these specifications and continue to function as expected.

System-level ESD

CX3 has built-in ESD protection on the D+, D-, and GND pins on the USB interface. The ESD protection levels provided on these ports are:

- ±2.2-kV human body model (HBM) based on JESD22-A114 specification
- ±6-kV contact discharge and ±8-kV air gap discharge based on IEC61000-4-2 level 3A using external system-level protection devices
- ± 8-kV contact discharge and ±15-kV air gap discharge based on IEC61000-4-2 level 4C using external system-level protection devices

This protection ensures that the device continues to function after ESD events up to the levels stated in this section.

The SSRX+, SSRX-, SSTX+, and SSTX- pins only have up to ±2.2-kV HBM internal ESD protection.

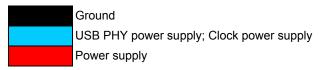


Pin Configuration

Figure 5. CX3 Ball Map (Top View)

A 1	A2	А3	A4	A5	A6	A7	A8	A9	A10	A11
U3VSSQ	U3RXVDDQ	SSRXM	SSRXP	SSTXP	SSTXM	AVDD	VSS	DP	DM	GPIO[24]
B1	B2	В3	B4	B5	В6	В7	B8	В9	B10	B11
VDDIO3	VSS	GPIO[23]	GPIO[21]	U3TXVDDQ	CVDDQ	AVSS	VSS	VSS	VDD	TRST#
C1	C2	C3	C4	C5	C6	C7	C8	C9	C10	C11
SPI_SSN / GPIO[54]	SPI_MISO / GPIO[55]	VDD	GPIO[26]	RESET#	GPIO[18]	GPIO[19]	GPI0[22]	GPIO[45]	TDO	I2S_MCLK / GPIO[57]
D1	D2	D3	D4	D5	D6	D7	D8	D9	D10	D11
I2S_CLK / GPIO[50]	I2S_SD / GPIO[51]	I2S_WS / GPIO[52]	SPI_SCK / GPIO[53]	SPI_MOSI / GPIO[56]	CLKIN_32	CLKIN	VSS	I2C_SCL	I2C_SDA	GPIO[17]
E1	E2	E3	E4	E5	E6	E7	E8	E9	E10	E11
UART_CTS / GPIO[47]	VSS	VDDIO2	UART_RX / GPIO[49]	UART_TX / GPIO[48]	GPIO[20]	TDI	TMS	VDD	VUSB	VSS
F1	F2	F3	F4	F5	F6	F7	F8	F9	F10	F11
DNU	REFCLK	GPIO[44]	XRST	UART_RTS / GPIO[46]	TCK	DNU	DNU	DNU	DNU	VDD
G1	G2	G3	G4	G5	G6	G7	G8	G9	G10	G11
VSS	XSHUTDOW N	MCLK	PMODE[0] / GPIO[30]	GPIO[25]	HSYNC_test	DNU	DNU	DNU	DNU	VSS
H1	H2	Н3	H4	H5	Н6	H7	Н8	Н9	H10	H11
VDD	DNU	DNU	PMODE[1] / GPIO[31]	VSYNC_test	MIPI RESET	DNU	PCLK_test	DNU	DNU	VDDIO1
J1	J2	J3	J4	J5	J6	J7	J8	J9	J10	J11
DNU	DNU	DNU	DNU	MIPI_D0P	MIPI_D1P ¹	MIPI_CP	MIPI_D2P ^{1, 2}	MIPI_D2N ^{1, 2}	DNU	VDD
K1	K2	К3	K4	K5	K6	K7	K8	K9	K10	K11
DNU	DNU	VSS	VSS	MIPI_D0N	MIPI_D1N ¹	MIPI_CN	MIPI_D3N ^{1, 2}	DNU	DNU	DNU
L1	L2	L3	L4	L5	L6	L7	L8	L9	L10	L11
VSS	VSS	VSS	PMODE[2] / GPIO[32]	VDD_MIPI	VSS	VDD	MIPI_D3P ^{1, 2}	VDDIO1	DNU	VSS

Legend



Unused MIPI input data lanes to be connected to GND.
 The signals MIPI_D2N, MIPI_D3N, and MIPI_D3P are not available in the CYUSB3064 part. These pins should be left "open" in the customer board.



Pin Description

Table 6. CYUSB306X Pin List

СХЗ				
Pin#	Pin name	I/O		
F10	DNU	I/O		
F9	DNU	I/O		
F7	DNU	I/O		
G10	DNU	I/O		
G9	DNU	I/O		
F8	DNU	I/O		
H10	DNU	I/O		
H9	DNU	I/O		
J10	DNU	I/O		
H7	DNU	I/O		
K11	DNU	I/O		
L10	DNU	I/O		
K10	DNU	I/O		
K9	DNU	I/O		
G7	DNU	I/O		
G8	DNU	I/O		
K2	DNU	I/O		
J4	DNU	I/O		
K1	DNU	I/O		
J2	DNU	I/O		
J3	DNU	I/O		
J1	DNU	I/O		
H2	DNU	I/O		
H3	DNU	I/O		
G6	HSYNC_test	I/O		
H5	VSYNC_test	I/O		
H8	PCLK_test	I/O		
	VDDIO1 Power Domain			
D11	GPIO[17]	I/O		
C6	GPIO[18]	I/O		
C7	GPIO[19]	I/O		
E6	GPIO[20]	I/O		
B4	GPIO[21]	I/O		
C8	GPIO[22]	I/O		
В3	GPIO[23]	I/O		
A11	GPIO[24]	I/O		
G5	GPIO[25]	I/O		

Table 6. CYUSB306X Pin List (continued)

CX3						
Pin#	Pin# Pin name I/O					
C4	GPIO[26]	I/O				
F3	GPIO[44]	I/O				
C9	GPIO[45]	I/O				
G4	PMODE[0] / GPIO[30]	I/O				
H4	PMODE[1] / GPIO[31]	I/O				
L4	PMODE[2] / GPIO[32]	I/O				
F1	DNU	I/O				
H6	MIPI RESET	I/O				
C5	RESET#	I				
F4	XRST	0				
G2	XSHUTDOWN	0				
G3	MCLK	0				
	VDDIO2 Power Domain	I				
F5	UART_RTS / GPIO[46]	I/O				
E1	UART_CTS / GPIO[47]	I/O				
E5	UART_TX / GPIO[48]	I/O				
E4	UART_RX / GPIO[49]	I/O				
D1	I2S_CLK / GPIO[50]	I/O				
D2	I2S_SD / GPIO[51]	I/O				
D3	D3 I2S_WS / GPI0[52]					
	VDDIO3 Power Domain					
D4	SPI_SCK / GPIO[53]	I/O				
C1	SPI_SSN / GPIO[54]	I/O				
C2	SPI_MISO / GPIO[55]	I/O				
D5	SPI_MOSI / GPIO[56]	I/O				
C11	I2S_MCLK / GPIO[57]	I/O				
U	SB Port (U3TXVDDQ/U3RXVDI Power Domain)	DQ				
A3	SSRXM	I				
A4	SSRXP	I				
A6	SSTXM	0				
A5 SSTXP		0				
USB Port (VUSB Power Domain)						
A9	DP	I/O				
A10	DM	I/O				
	VDDIO1 Power Domain					
F2	REFCLK					
VDD_MIPI Power Domain						
J7	MIPI_CP	I				



Table 6. CYUSB306X Pin List (continued)

	CX3				
Pin#	Pin name	I/O			
K7	MIPI_CN	I			
J5	MIPI_D0P	I			
K5	MIPI_D0N	I			
J6	MIPI_D1P ¹	I			
K6	MIPI_D1N ¹	I			
J9	MIPI_D2N ^{1, 2}	I			
J8	MIPI_D2P ^{1, 2}	I			
L8	MIPI_D3P ^{1, 2}	I			
K8	MIPI_D3N ^{1, 2}	I			
	CVDDQ Power Domain				
D7	CLKIN	I			
D6	CLKIN_32	I			
	VDDIO1 Power Domain				
D9	I2C_SCL	I/O			
D10	I2C_SDA	I/O			
E7	TDI	I			
C10	TDO	0			
B11	TRST#	I			
E8	TMS	I			
F6	TCK	I			
	Power Domains				
E10	VUSB	PWR			
A1	U3VSSQ	PWR			
H11	VDDIO1	PWR			
L9	VDDIO1	PWR			
E3	VDDIO2	PWR			
B1	VDDIO3	PWR			
В6	CVDDQ	PWR			
B5	U3TXVDDQ	PWR			
A2	U3RXVDDQ	PWR			
A7	AVDD	PWR			
В7	AVSS	PWR			
L5	VDD_MIPI	PWR			
B10	VDD	PWR			
J11	VDD	PWR			
C3	VDD	PWR			
E9	VDD	PWR			
F11	VDD	PWR			
H1	VDD	PWR			

Table 6. CYUSB306X Pin List (continued)

	CX3	
Pin#	Pin name	I/O
L7	VDD	PWR
D8	VSS	PWR
E2	VSS	PWR
E11	VSS	PWR
G1	VSS	PWR
A8	VSS	PWR
G11	VSS	PWR
L1	VSS	PWR
B8	VSS	PWR
L6	VSS	PWR
B2	VSS	PWR
L11	VSS	PWR
В9	VSS	PWR
K4	VSS	PWR
L3	VSS	PWR
K3	VSS	PWR
L2	VSS	PWR

- Unused MIPI input data lanes to be connected to GND.
 The signals MIPI_D2N, MIPI_D2P, MIPI_D3N, and MIPI_D3P are not available in the CYUSB3064 part. These pins should be left "open" in the customer board.



Absolute Maximum Ratings

Exceeding maximum ratings may shorten the useful life of the device.
Storage temperature –65 °C to +150 °C
Supply voltage to ground potential V _{DD} , A _{VDDQ} 1.25 V
V _{DDIO1} , V _{DDIO2} , V _{DDIO3}
U3TX _{VDDQ} , U3RX _{VDDQ} 1.25 V
DC input voltage to any input pinV _{CC} + 0.3
DC voltage applied to outputs in high Z state (V _{CC} is the corresponding I/O voltage)V _{CC} + 0.3
Maximum latch-up current140 mA
Maximum output short-circuit current for all I/O configurations. (V _{OUT} = 0 V) –100 mA

Operating Conditions

T _A (ambient temperature under bias) Industrial	40 °C to +85 °C
V _{DD} , A _{VDDQ} , U3TX _{VDDQ} , U3RX _{VDDQ} Supply voltage	1.15 V to 1.25 V
V _{USB} supply voltage	4 V to 6 V
V _{DDIO1} , V _{DDIO2} , V _{DDIO3} , C _{VDDQ} Supply voltage	1.7 V to 3.6 V

DC Specifications

Parameter	Description	Min	Max	Units	Notes
V_{DD}	Core voltage supply	1.15	1.25	V	1.2-V typical
A _{VDD}	Analog voltage supply	1.15	1.25	V	1.2-V typical
V _{DD_MIPI}	MIPI bridge D-PHY supply voltage	1.15	1.25	V	1.2-V typical
V _{DDIO1}	I ² C, JTAG and GPIO power domain	1.7	3.6	V	1.8-, 2.5-, and 3.3-V typical
$V_{\rm DDIO2}$	UART/I ² S power supply domain	1.7	3.6	V	1.8-, 2.5-, and 3.3-V typical
$V_{\rm DDIO3}$	SPI/I ² S power supply domain	1.7	3.6	V	1.8-, 2.5-, and 3.3-V typical
V _{USB}	USB voltage supply	4	6	V	5-V typical
U3TX _{VDDQ}	USB 3.0 1.2-V supply	1.15	1.25	V	1.2-V typical. A 22-µF bypass capacitor is required on this power supply.
U3RX _{VDDQ}	USB 3.0 1.2-V supply	1.15	1.25	٧	1.2-V typical. A 22-µF bypass capacitor is required on this power supply.
C _{VDDQ}	Clock voltage supply	1.7	3.6	V	1.8-, 3.3-V typical
V _{IH1}	Input HIGH voltage 1	0.625 × V _{CC}	V _{CC} + 0.3	V	For 2.0 V \leq V _{CC} \leq 3.6 V (except USB and MIPI CSI-2 pins).V _{CC} is the corresponding I/O voltage supply.
V _{IH2}	Input HIGH voltage 2	V _{CC} – 0.4	V _{CC} + 0.3	V	For 1.7 V \leq V _{CC} \leq 2.0 V (except USB USB and MIPI CSI-2 pins).V _{CC} is the corresponding I/O voltage supply.
V _{IL}	Input LOW voltage	-0.3	0.25 × V _{CC}	V	V _{CC} is the corresponding I/O voltage supply.
V _{OH}	Output HIGH voltage	0.9 × V _{CC}	-	٧	I_{OH} (max) = -100 μ A tested at quarter drive strength. V_{CC} is the corresponding I/O voltage supply.
V _{OL}	Output LOW voltage	-	0.1 × V _{CC}	٧	I_{OL} (min) = +100 μ A tested at quarter drive strength. V_{CC} is the corresponding I/O voltage supply.



DC Specifications (continued)

Parameter	Description	Min	Max	Units	Notes
I _{IX}	Input leakage current for all pins except SSTXP/SSXM/SSRXP/SSRXM	-1	1	μА	All I/O signals held at V _{DDQ} (For I/Os with a pull-up or pull-down resistor connected, the leakage current increases by V _{DDQ} /R _{PU} or V _{DDQ} /R _{PD})
I _{OZ}	Output High-Z leakage current for all pins except SSTXP/ SSXM/ SSRXP/SSRXM and MIPI CSI-2 signals	-1	1	μA	All I/O signals held at V _{DDQ}
I _{CC} Core	Core and analog voltage operating current	-	192	mA	Total current through A _{VDD} , V _{DD}
I _{CC} USB	USB voltage supply operating current	-	60	mA	-
	Total suspend current during	Core: 558.35 µA	-	μA	Core Current is measured through
I _{SB1}	suspend mode with USB 3.0 PHY	I/O: 4.58 μA	-	μA	V _{DD} , A _{VDD} and V _{DD_MIPI} .
	enabled	USB: 4672 μA	-	μA	I/O Current is measured through
	Total day III	Core: 148.31 µA	-	μA	V _{DDIO1} to V _{DDIO3} .
I _{SB3}	Total standby current during core power-down mode	I/O: 3.16 μA	-	μA	USB Current is measured through
	perior donn mode	USB: 15.8 μA	-	μA	$V_{\rm USB}$, U3TX $_{\rm VDDQ}$ and U3RX $_{\rm VDDQ}$.
V _{RAMP}	Voltage ramp rate on core and I/O supplies	0.2	12	V/ms	Voltage ramp must be monotonic
V _N	Noise level permitted on V _{DD} and I/O supplies	-	100	mV	Max p-p noise level permitted on all supplies except A _{VDD}
V _{N_AVDD}	Noise level permitted on A _{VDD} supply	_	20	mV	Max p-p noise level permitted on A _{VDD}

MIPI D-PHY Electrical Characteristics

Parameter	Description		Spec			
Parameter	Description	Min	Nom	Max	Unit	
MIPI D-PHY	RX DC Characteristics	•	•		•	
V_{PIN}	Pin signal voltage range	-50	_	1350	mV	
V _{IH}	Logic 1 input voltage	880	_	_	mV	
V_{IL}	Logic 0 input voltage	-	-	550	mV	
V _{CMRX (DC)}	Common-mode voltage HS receiver mode	70	_	330	mV	
V_{IDTH}	Differential input high threshold		_	70	mV	
V_{IDTL}	Differential input low threshold	–70	_	-	mV	
V _{IHHS}	Single-ended input high voltage		_	460	mV	
V_{ILHS}	Single-ended input low voltage	-40	_	_	mV	



AC Timing Parameters

MIPI Data to Clock Timing Reference

Figure 6. MIPI CSI Signal Data to Clock Timing Reference

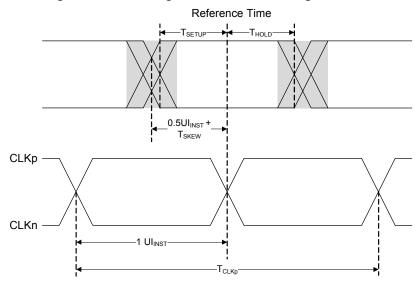


Table 7. MIPI Data to Clock Timing Reference

Parameter	Description	Min	Max	Units
T _{SKEW}	Data to clock skew measured at the transmitter	-0.15	0.15	UI _{INST}
T _{SETUP}	Data to clock setup time at receiver	0.15	_	UI _{INST}
T _{HOLD}	Clock to data hold time at receiver	0.15	_	UI _{INST}
UI _{INST}	One data bit time (instantaneous)	1	12.5	ns
T _{CLKp}	Period of dual data rate clock	2	25	ns

Reference Clock Specifications

Table 8. Reference Clock Specifications

Parameter	Description	Min	Max	Units	Notes
RefClk	Reference clock frequency	6	40	MHz	_
RefclkDutyCyl	Duty cycle	40%	60%	_	-
RefClkPJ	Reference clock input period jitter	-100	100	ps	-



MIPI CSI Signal Low Power AC Characteristics

Input

espike

2*T_{LPX}

2*T_{LPX}

V_{II}

espike

T_{MIN-RX}

Figure 7. MIPI CSI bus Input Glitch Rejection

Table 9. MIPI CSI Signal Low Power AC Characteristics

Output

Parameter	Description	Min	Max	Units	Notes
e _{SPIKE}	Input noise rejection	-	300	V.ps	Time-voltage integration of a spike above V_{IL} when being in LP-0 or below V_{IH} when being in LP-1 state. An impulse less than this will not change the receiver state.
T _{MIN-RX}	Minimum pulse width response	20	-	ns	An input pulse greater than this shall toggle the output.
V _{INT}	peak interference amplitude	-	200	mV	-
F _{INT}	Interference frequency	450	-	MHz	-
T _{LPX}	Length of any low power state period	50	-	ns	-

AC Specifications

Table 10. AC Specifications

Parameter	Description	Min	Max	Units	Details / Conditions
I // \/ · · · ·	Common-mode interference beyond 450 MHz	1	100	mV	$\Delta V_{CMRX(HF)}$ is the peak amp. Of a sine wave superimposed on the receiver inputs.
// // a	Common-mode interference beyond 50 - 450 MHz	-50	50	mV	Excluding static ground shift of 50 mV. Voltage difference compared to the DC average common-mode potential



Serial Peripherals Timing

I²C Timing

Figure 8. I²C Timing Definition

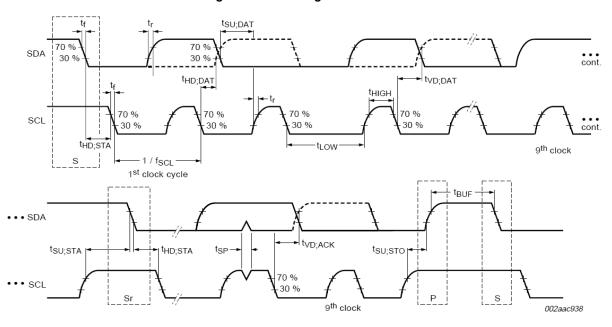


Table 11. I²C Timing Parameters^[2]

Parameter	Description	Min	Max	Units
	I ² C Standard Mode Parameters	•		
f _{SCL}	SCL clock frequency	0	100	kHz
t _{HD:STA}	Hold time START condition	4	_	μs
t_{LOW}	LOW period of the SCL	4.7	_	μs
t _{HIGH}	HIGH period of the SCL	4	_	μs
t _{SU:STA}	Setup time for a repeated START condition	4.7	_	μs
t _{HD:DAT}	Data hold time	0	_	μs
t _{SU:DAT}	Data setup time	250	_	ns
t _r	Rise time of both SDA and SCL signals	-	1000	ns
t _f	Fall time of both SDA and SCL signals	_	300	ns
t _{SU:STO}	Setup time for STOP condition	4	_	μs
t _{BUF}	Bus free time between a STOP and START condition	4.7	_	μs
t _{VD:DAT}	Data valid time	-	3.45	μs
t _{VD:ACK}	Data valid ACK	-	3.45	μs
t _{SP}	Pulse width of spikes that must be suppressed by input filter	n/a	n/a	

Note

^{2.} All parameters guaranteed by design and validated through characterization.



Table 11. I²C Timing Parameters^[2] (continued)

thdist thold t tLOW LOW thigh HIGH tsu:sta Setup thd:day Data t tsu:day Data s tr Rise t tf Fall tir	I ² C Fast Mode Parameters lock frequency ime START condition period of the SCL period of the SCL time for a repeated START condition hold time setup time me of both SDA and SCL signals	0 0.6 1.3 0.6 0.6 0	400 - - - -	kHz µs µs µs µs
thD:STA Hold to the total tota	ime START condition period of the SCL period of the SCL time for a repeated START condition hold time setup time	0.6 1.3 0.6 0.6		µs µs µs
$\begin{array}{cccc} t_{LOW} & LOW \\ t_{HIGH} & HIGH \\ t_{SU:STA} & Setup \\ t_{HD:DAT} & Data & t_{SU:DAT} \\ t_r & Rise & t_f & Fall & tir \\ \end{array}$	period of the SCL period of the SCL time for a repeated START condition nold time setup time	1.3 0.6 0.6 0	- - -	μs μs
thigh High tsu:sta Setup thd:dat tsu:dat tr Rise t tf Fall tir	period of the SCL time for a repeated START condition nold time setup time	0.6 0.6 0		μs
$\begin{array}{ccc} t_{SU:STA} & Setup \\ t_{HD:DAT} & Data & t_{SU:DAT} & Data & t_{r} & Rise & t_{f} & Fall & tir \\ \end{array}$	time for a repeated START condition nold time setup time	0.6	-	+ -
t _{HD:DAT} Data t t _{SU:DAT} Data s t _r Rise ti	nold time setup time	0	_	μs
$t_{SU:DAT}$ Data s t_r Rise ti t_f Fall tir	setup time			
t _r Rise ti	·	100	_	μs
t _f Fall tir	me of both SDA and SCL signals	100	_	ns
		_	300	ns
t. Sotup	ne of both SDA and SCL signals	_	300	ns
t _{SU:STO} Setup	time for STOP condition	0.6	_	μs
t _{BUF} Bus fr	ee time between a STOP and START condition	1.3	_	μs
t _{VD:DAT} Data v	ralid time	_	0.9	μs
t _{VD:ACK} Data v	ralid ACK	_	0.9	μs
t _{SP} Pulse	width of spikes that must be suppressed by input filter	0	50	ns
	I ² C Fast Mode Plus Parameters			
f _{SCL} SCL o	lock frequency	0	1000	kHz
t _{HD:STA} Hold t	ime START condition	0.26	_	μs
t _{LOW} LOW	period of the SCL	0.5	_	μs
t _{HIGH} HIGH	period of the SCL	0.26	_	μs
t _{SU:STA} Setup	time for a repeated START condition	0.26	_	μs
t _{HD:DAT} Data I	nold time	0	_	μs
t _{SU:DAT} Data s	setup time	50	_	ns
t _r Rise t	me of both SDA and SCL signals	_	120	ns
t _f Fall tir	ne of both SDA and SCL signals	_	120	ns
t _{SU:STO} Setup	time for STOP condition	0.26	_	μs
t _{BUF} Bus-fr	ee time between a STOP and START condition	0.5	_	μs
t _{VD:DAT} Data v	ralid time	_	0.45	μs
t _{VD:ACK} Data v	ralid ACK	_	0.55	μs
t _{SP} Pulse	width of spikes that must be suppressed by input filter	0	50	\neg



*I*²S Timing Diagram

Figure 9. I²S Transmit Cycle

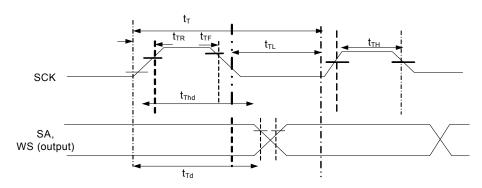


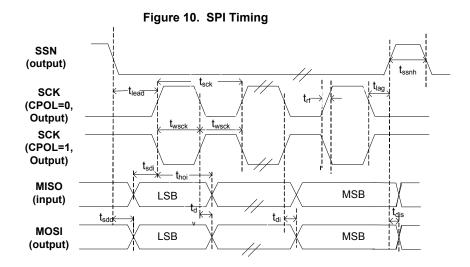
Table 12. I²S Timing Parameters^[3]

Parameter	Description Min Max Un							
t _T	I ² S transmitter clock cycle	t _{TR}	-	ns				
t _{TL}	I ² S transmitter cycle LOW period	0.35 t _{TR}	-	ns				
t _{TH}	I ² S transmitter cycle HIGH period	0.35 t _{TR}	-	ns				
t _{TR}	I ² S transmitter rise time	_	0.15 t _{TR}	ns				
t _{TF}	S transmitter fall time – 0.15 t _{TR} ns							
t _{Thd}	6 transmitter data hold time 0 - ns							
t _{Td}	I ² S transmitter delay time – 0.8 t _T ns							
Note t_T is selectable through clock gears. Max t_{TR} is designed for 96-kHz codec at 32 bits to be 326 ns (3.072 MHz).								

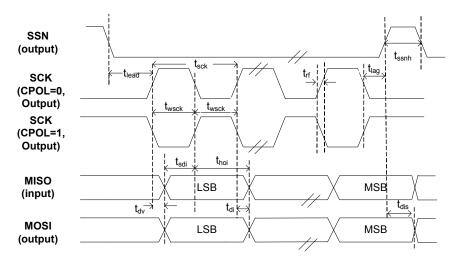
Note
3. All parameters guaranteed by design and validated through characterization.



SPI Timing Specification



SPI Master Timing for CPHA = 0



SPI Master Timing for CPHA = 1



Table 13. SPI Timing Parameters [4]

Parameter	Description	Min	Max	Units
f _{op}	Operating frequency	0	33	MHz
t _{sck}	Cycle time	30	_	ns
t _{wsck}	Clock HIGH/LOW time	13.5	_	ns
t _{lead}	SSN-SCK lead time	1/2 t _{sck} ^[5] – 5	1.5 t _{sck} ^[5] + 5	ns
t _{lag}	Enable lag time	0.5	1.5 t _{sck} ^[5] + 5	ns
t _{rf}	Rise/fall time	_	8	ns
t _{sdd}	Output SSN to valid data delay time	_	5	ns
t _{dv}	Output data valid time	_	5	ns
t _{di}	Output data invalid	0	_	ns
t _{ssnh}	Minimum SSN HIGH time	10	_	ns
t _{sdi}	Data setup time input	8	_	ns
t _{hoi}	Data hold time input	0	_	ns
t _{dis}	Disable data output on SSN HIGH	0	_	ns

Notes

All parameters guaranteed by design and validated through characterization.
 Depends on LAG and LEAD setting in the SPI_CONFIG register.

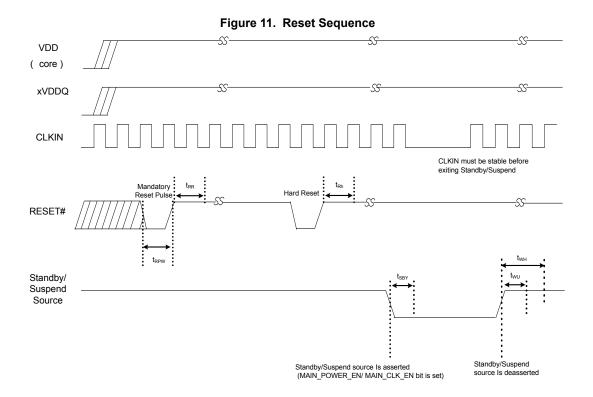


Reset Sequence

CX3's hard reset sequence requirements are specified in this section.

Table 14. Reset and Standby Timing Parameters

Parameter	Definition	Conditions	Min (ms)	Max (ms)
t _{RPW}	Minimum RESET# pulse width	Clock Input	1	-
t _{RH}	Minimum HIGH on RESET#	-	5	_
t _{RR}	Reset recovery time (after which the boot loader begins firmware download)	Clock Input	1	_
t _{SBY}	Time to enter standby/suspend mode (from the time MAIN_CLOCK_EN/ MAIN_POWER_EN bit is set)	-	-	1
t _{WU}	Time to wakeup from standby	Clock Input	1	-
t _{WH}	Minimum time before standby/suspend source may be reasserted	-	5	_



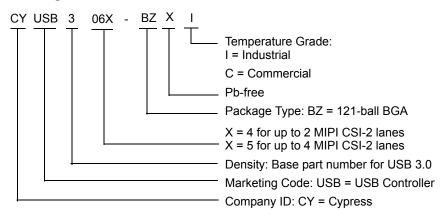


Ordering Information

Table 15. Ordering Information

Ordering Code	MIPI CSI-2 Lanes	Package Type	Temperature Grade
CYUSB3065-BZXI	4	121-ball BGA	Industrial
CYUSB3065-BZXC	4	121-ball BGA	Commercial
CYUSB3064-BZXI	2	121-ball BGA	Industrial
CYUSB3064-BZXC	2	121-ball BGA	Commercial

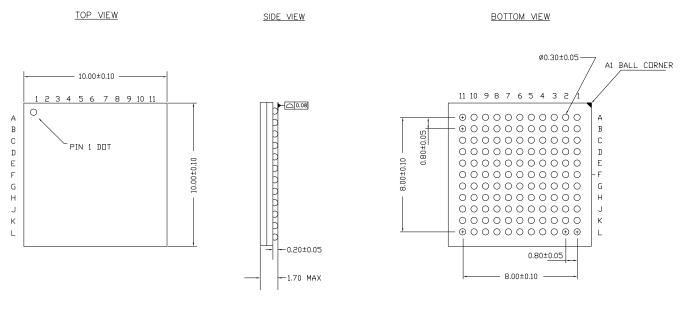
Ordering Code Definitions





Package Diagram

Figure 12. 121-ball BGA (10 \times 10 \times 1.7 mm) Package Outline, 001-87293



NOTES:

- 1. ALL DIMENSIONS ARE IN MILLIMETERS
- 2. REFERENCE JEDEC : PUB 95, DESIGN GUIDE 4.5

001-87293 **



Acronyms

Table 16. Acronyms Used in this Document

Acronym	Description			
CSI - 2	Camera Serial Interface - 2			
DMA	Direct Memory Access			
DNU	Do Not Use			
HNP	Host Negotiation Protocol			
MIPI	Mobile Industry Processor Interface			
MMC	Multimedia Card			
MTP	Media Transfer Protocol			
PLL	Phase Locked Loop			
PMIC	Power Management IC			
SD	Secure Digital			
SDIO	Secure Digital Input / Output			
SLC	Single-Level Cell			
SPI	Serial Peripheral Interface			
SRP	Session Request Protocol			
USB	Universal Serial Bus			
WLCSP	Wafer Level Chip Scale Package			

Document Conventions

Units of Measure

Table 17. Units of Measure

Symbol	Unit of Measure				
°C	degree Celsius				
Mbps	Megabits per second				
MBps	Megabytes per second				
MHz	megahertz				
μA	microampere				
μs	microsecond				
mA	milliampere				
ms	millisecond				
ns	nanosecond				
Ω	ohm				
pF	picofarad				
V	volt				



Errata

This section describes the errata for CX3. Details include errata trigger conditions, scope of impact, available workaround, and silicon revision applicability. Contact your local Cypress Sales Representative if you have questions.

Part Numbers Affected

Part Number	Device Characteristics
CYUSB306x-xxxx	All Variants

Qualification Status

Product Status: Production

Errata Summary

The following table defines the errata applicability to available EZ-USB CX3 SuperSpeed USB Controller family devices.

Items	[Part Number]	Silicon Revision	Fix Status
Turning off VDDIO1 during Normal, Suspend, and Standby modes causes the CX3 to stop working.	CYUSB306x-xxxx	All	Workaround provided
USB enumeration failure in USB boot mode when CX3 is self-powered.	CYUSB306x-xxxx	All	Workaround provided
Extra ZLP is generated by the COMMIT action in the GPIF II state.	CYUSB306x-xxxx	All	Workaround provided
4. Invalid PID Sequence in USB 2.0 ISOC data transfer.	CYUSB306x-xxxx	All	Workaround provided
USB data transfer errors are seen when ZLP is followed by data packet within same microframe.	CYUSB306x-xxxx	All	Workaround provided
Bus collision is seen when the I2C block is used as a master in the I2C Multi-master configuration.	CYUSB306x-xxxx	All	Use CX3 in single-master configuration

1. Turning off VDDIO1 during Normal, Suspend, and Standby modes causes the CX3 to stop working.

■ Problem Definition

Turning off the VDDIO1 during Normal, Suspend, and Standby modes will cause the CX3 to stop working.

■ Parameters Affected

N/A

■ Trigger Conditions

This condition is triggered when the VDDIO1 is turned off during Normal, Suspend, and Standby modes.

■ Scope Of Impact

CX3 stops working.

■ Workaround

VDDIO1 must stay on during Normal, Suspend, and Standby modes.

■ Fix Status

No fix. Workaround is required.



2. USB enumeration failure in USB boot mode when CX3 is self-powered.

■ Problem Definition

CX3 device may not enumerate in USB boot mode when it is self-powered. The bootloader is designed for bus power mode. It does not make use of the VUSB pin on the USB connector to detect the USB connection and expect that USB bus is connected to host if it is powered. If CX3 is not already connected to the USB host when it is powered, then it enters into low-power mode and does not wake up when connected to USB host.

■ Parameters Affected

N/A

■ Trigger Conditions

This condition is triggered when CX3 is self-powered in USB boot mode.

■ Scope of Impact

Device does not enumerate

■ Workaround

Reset the device after connecting to USB host.

■ Fix Status

No fix. Workaround is required.

3. Extra ZLP is generated by the COMMIT action in the GPIF II state.

■ Problem Definition

When COMMIT action is used in a GPIF-II state without IN_DATA action then an extra Zero Length Packet (ZLP) is committed along with the data packets.

■ Parameters Affected

N/A

■ Trigger Conditions

This condition is triggered when COMMIT action is used in a state without IN_DATA action.

■ Scope of Impact

Extra ZLP is generated.

■ Workaround

Use IN_DATA action along with COMMIT action in the same state.

■ Fix Status

No fix. Workaround is required.



4. Invalid PID Sequence in USB 2.0 ISOC data transfer.

■ Problem Definition

When the CX3 device is functioning as a high speed USB device with high bandwidth isochronous endpoints, the PID sequence of the ISO data packets is governed solely by the isomult setting. The length of the data packet is not considered while generating the PID sequence during each microframe. For example, even if a short packet is being sent on an endpoint with MULT set to 2; the PID used will be DATA2.

■ Parameters Affected

N/A

■ Trigger Conditions

This condition is triggered when high bandwidth ISOC transfer endpoints are used.

■ Scope of Impact

ISOC data transfers failure.

■ Workaround

This problem can be worked around by reconfiguring the endpoint with a lower isomult setting prior to sending short packets, and then switching back to the original value.

■ Fix Status

No fix. Workaround is required.

5. USB data transfer errors are seen when ZLP is followed by data packet within same microframe.

■ Problem Definition

Some data transfer errors may be seen if a Zero Length Packet is followed very quickly (within one microframe or 125 μs) by another data packet on a burst enabled USB IN endpoint operating at super speed.

■ Parameters Affected

N/A

■ Trigger Conditions

This condition is triggered in SuperSpeed transfer with ZLPs.

■ Scope of Impact

Data failure and lower data speed.

■ Workaround

The solution is to ensure that some time is allowed to elapse between a ZLP and the next data packet on burst enabled USB IN endpoints. If this cannot be ensured at the data source, the CyU3PDmaChannelSetSuspend() API can be used to suspend the corresponding USB DMA socket on seeing the EOP condition. The channel operation can then be resumed as soon as the suspend callback is received.

■ Fix Status

No fix. Workaround is required.



6. Bus collision is seen when the I²C block is used as a master in the I²C Multi-master configuration.

■ Problem Definition

When CX3 is used as a master in the I²C multi-master configuration, there can be occasional bus collisions.

■ Parameters Affected

NA

■ Trigger Conditions

This condition is triggered only when the CX3 I²C block operates in Multi-master configuration.

■ Scope of Impact

The CX3 I²C block can transmit data when the I²C bus is not idle leading to bus collision.

■ Workaround

Use CX3 as a single master.

■ Fix Status

No fix.



Document History Page

Revision	ECN	Orig. of Change	Submission Date	Description of Change
**	3994736	KUMR	05/09/2013	New datasheet
*A	4065766	KUMR	07/17/2013	Updated Logic Block Diagram. Updated Pin Description. Updated DC Specifications. Replaced "VBUS" and "VBATT" by "VUSB" in all instances across the document. Updated in new template.
*B	4080302	KUMR	07/29/2013	Updated status as "Preliminary".
*C	4088328	KUMR	08/06/2013	Updated Pin Configuration (Updated Figure).
*D	4113754	KUMR	09/04/2013	Updated Clocking: Added a Note at the bottom of section. Updated Pin Description. Updated Table 6. Updated DC Specifications: Updated description of V _{DDIO2} parameter. Updated description of V _{DDIO3} parameter. Changed maximum value of I _{CC} Core parameter from 200 mA to 380 mA.
*E	4188453	KUMR	11/14/2013	Changed status from Preliminary to Final. Updated Features: Updated description. Updated Applications: Updated description. Updated Logic Block Diagram. Updated Functional Overview. Updated MIPI CSI-2 RX Interface. Updated Additional Outputs: Updated description. Updated Reset. Updated Soft Reset: Updated description. Updated Power. Updated Power Modes. Updated Table 5. Updated "Methods of Entry" corresponding to "Suspend Mode with USB 3.0 PHY Enabled". Updated "Characteristics" corresponding to "Standby Mode". Updated EMI: Updated description. Updated EMI: Updated description. Updated Pin Configuration: Updated details of G4, H4, L4, F1, F5, E1, E5, E4, D1, D2, D3, D4, C1, C2, D5, C11 pins in Figure . Updated Pin Description. Updated Pin Description. Updated details in "Pin name" column for G4, H4, L4, F1, F5, E1, E5, E4, D1 D2, D3, D4, C1, C2, D5, C11 pins. Updated Absolute Maximum Ratings: Removed "Ambient temperature with power applied". Removed "Static discharge voltage ESD protection levels". Renamed "Latch-up current" as "Maximum latch-up current" and updated the values. Updated DC Specifications: Updated DC Specifications: Updated details in "Notes" column corresponding to V _{IH1} and V _{IH2} parameters Updated details in "Notes" column corresponding to I _{SB1} and I _{SB3} parameters. Updated MIPI D-PHY Electrical Characteristics. Updated MIPI D-PHY Electrical Characteristics. Updated MIPI Data to Clock Timing Reference.



Document History Page (continued)

Document	Number: 00		Submission	
Revision	ECN	Orig. of Change	Submission Date	Description of Change
*E (cont.)	4188453	KUMR	11/14/2013	Updated Figure 6. Updated Table 7. Updated minimum value of UI _{INST} parameter. Updated maximum value of T _{CLKp} parameter. Updated MIPI CSI Signal Low Power AC Characteristics: Updated Figure 7. Updated Serial Peripherals Timing. Updated I2C Timing. Updated Table 11: Removed "(Not supported at I2C_VDDQ = 1.2 V)" in "I ² C Fast Mode Plus Parameters" sub-heading. Updated Reset Sequence. Updated Table 14. Removed "Crystal Input" condition for t _{RPW} , t _{RR} , t _{WU} parameters. Updated Figure 11. Updated Ordering Information: Updated part numbers.
*F	4214952	RAJA	03/12/2014	Updated Features. Updated Functional Overview. Updated Application Examples. Updated Figure 1. Updated Configuration Options: Added email. Updated Pin Description. Updated caption of Table 6. Updated DC Specifications: Updated maximum value of V _{IL} parameter. Updated maximum value of V _{RAMP} parameter. Updated AC Timing Parameters. Updated MIPI CSI Signal Low Power AC Characteristics. Updated Table 9. Updated details in "Notes" column. Updated to new template.
*G	4417040	KUMR	06/23/2014	Updated Power: Updated details of IO_VDDQ power supply domain. Updated DC Specifications: Updated maximum value of I _{CC} Core parameter.
*H	4467092	RAJA	08/06/2014	Added new part numbers: 2 and 4 MIPI CSI-2 lane parts with Industrial and Commercial temperature grades. HSYNC, VSYNC, PCLK test points mentioned in the pin configuration table MCLK - Signal description updated. Updated information for CYUSB3064 part number: MIPI_D2P, MIPI_D2N, MIPI_D3P, MIPI_D3N signals not available.
*	4862446	RAGO	08/13/2015	Added footnote 1, and updated Pin Configuration (Figure 5) and Pin Description (Table 6) to indicate grounding of unused MIPI lanes.
*J	4974015	RAGO	10/19/2015	Added More Information.
*K	5283275	RAGO	05/24/2016	Updated to new template. Completing Sunset Review.



Document History Page (continued)

Document Title: CYUSB306X, EZ-USB [®] CX3: MIPI CSI-2 to SuperSpeed USB Bridge Controller Document Number: 001-87516							
Revision	ECN	Orig. of Change	Submission Date	Description of Change			
*L	5464498	RAJA	06/22/2017	Updated Power: Updated description. Updated Operating Conditions: Replaced "3.2 V" with "4 V" in Operating Conditions corresponding to "V _{USB} supply voltage". Updated DC Specifications: Changed minimum value of V _{USB} parameter from 3.2 V to 4 V. Added Errata. Updated to new template.			



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